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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10077538	FILING DATE 02/15/2002	CLASS 36129	SUBCLASS 832	GAU 370 2841	EXAMINER Abes
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**APPLICANTS: Yee Lup; Belmas Darrell;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO SC11328ZK
TITLE : Process and apparatus for disengaging semiconductor die from an adhesive film U.S. DEPT. OF COMM./PAT. & TM-PTO-4361 (Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		PREPARED FOR ISSUE		
		Application Examiner		
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